

20-Channel, Serial-Input, Vacuum-Fluorescent Display Driver for Anode/Grid

Features

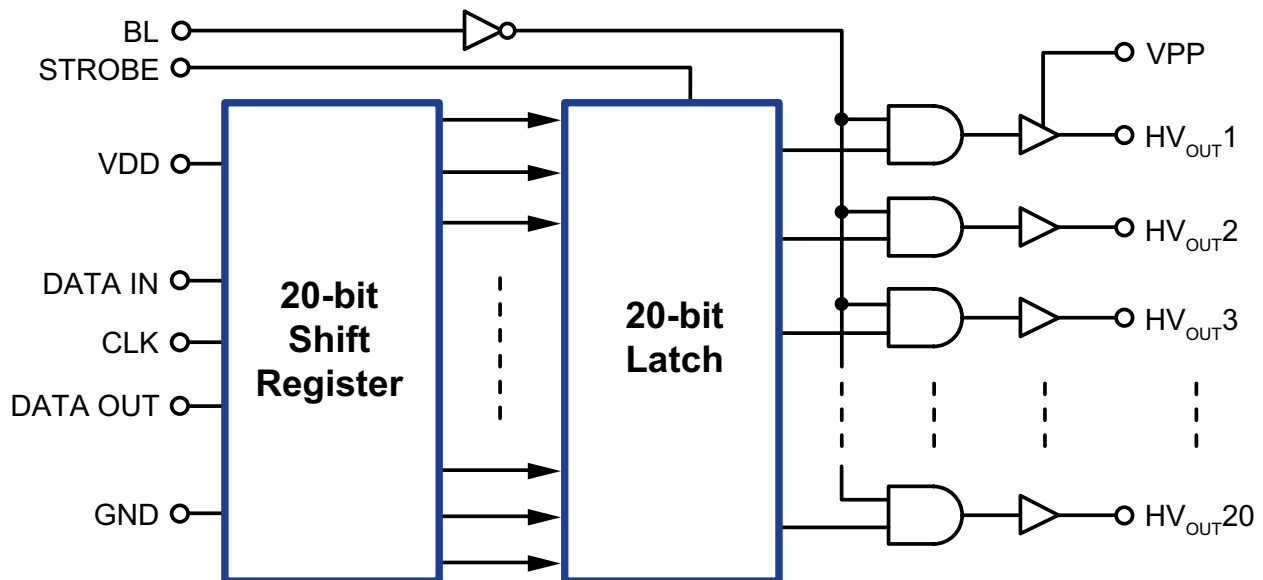
- ▶ HVCMOS® technology for high performance
- ▶ Operating voltage up to 80V
- ▶ High speed source driver
- ▶ 5.0V CMOS logic circuitry
- ▶ Up to 5.0MHz data input rate
- ▶ Excellent noise immunity
- ▶ Flexible high voltage supplies

General Description

The Supertex HV5812 is a 20-channel, serial input, vacuum-fluorescent display driver. It combines a 20-bit CMOS shift register, data latches, and control circuitry with high voltage MOSFET outputs. The HV5812 is primarily designed for vacuum-fluorescent displays.

The CMOS shift register and latches allow direct interfacing with microprocessor based systems. Data input rates are typically over 5.0MHz with 5.0V logic supply. Especially useful for interdigit blanking, the BLANKING input disables the output source drives and turns on the sink drivers. Use with TTL may require external pull-up resistors to ensure an input logic high.

Functional Block Diagram



Ordering Information

Device	28-Lead PDIP (.600in row spacing) 1.565x.580in body .250in height (max) .100in pitch	28-Lead PLCC .453x.453in body .180in height (max) .050in pitch	28-Lead SOW 17.90x7.50mm body 2.65mm height (max) 1.27mm pitch
HV5812	HV5812P-G	HV5812PJ-G	HV5812WG-G

-G indicates package is RoHS compliant ("Green")



Absolute Maximum Ratings

Parameter	Value
Supply voltage, V_{DD}	-0.5V to +7.5V
Supply voltage, V_{PP}	-0.5V to +90V
Logic input levels	-0.3V to $V_{DD} + 0.3V$
Maximum junction temperature	125°C
Storage temperature range	-55°C to +150°C
Power dissipation:	
28-Lead PDIP (P)	2000mW
28-Lead PLCC (PJ)	1900mW
28-Lead SOW (WG)	1700mW

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to GND.

Recommended Operating Conditions

Sym	Parameter	Min	Max	Units
V_{DD}	Supply voltage	4.5	5.5	V
V_{PP}	Supply voltage	20	80	V
T_j	Operating junction temperature	-40	+125	°C

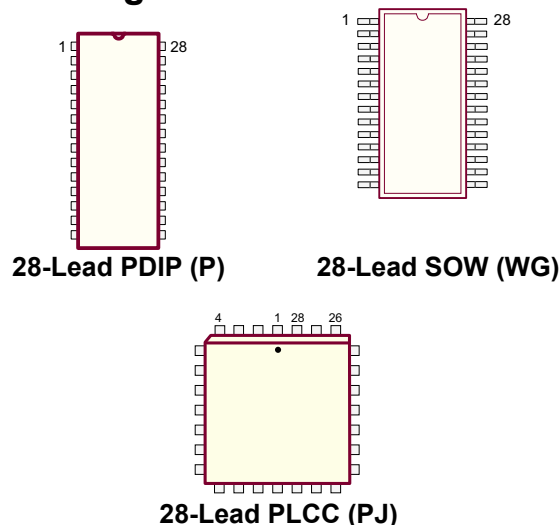
Power-up sequence should be the following:

1. Connect ground.
2. Apply V_{DD} .
3. Set all inputs (Data, CLK, etc.) to a known state.
4. Apply V_{PP} .

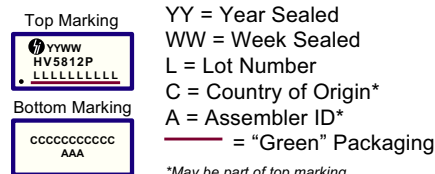
The V_{PP} should not drop below V_{DD} during operation.

Power-down sequence should be the reverse of the above.

Pin Configurations

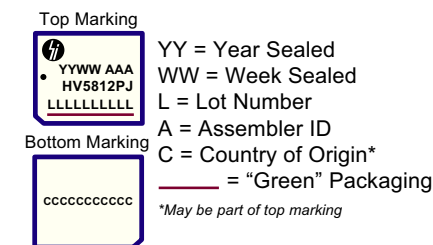


Product Marking



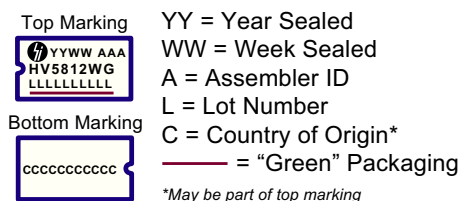
Package may or may not include the following marks: Si or

28-Lead PDIP (P)



Package may or may not include the following marks: Si or

28-Lead PLCC (PJ)



Package may or may not include the following marks: Si or

28-Lead SOW (WG)

Electrical Characteristics

DC Characteristics (over recommended operating conditions, $T_A = 25^\circ\text{C}$, unless otherwise noted)

Sym	Parameter	Min	Typ	Max	Units	Conditions	
I_{DSS}	Output leakage current	-	-5.0	-15	μA	$V_{OUT} = 0\text{V}$, $T_A = +70^\circ\text{C}$	
V_{OH}	High-level output	HV _{OUT}	78	78.5	-	V	$I_{OUT} = -25\text{mA}$, $V_{PP} = 80\text{V}$, $T_j = +25^\circ\text{C}$
			77	78	-		$I_{OUT} = -25\text{mA}$, $V_{PP} = 80\text{V}$, $T_j = +125^\circ\text{C}$
		DATA OUT	4.5	4.7	-	V	$I_{OUT} = -200\mu\text{A}$, $V_{DD} = 5.0\text{V}$
V_{OL}	Low-level output	HV _{OUT}	-	1.5	3.0	V	$I_{OUT} = 1.0\text{mA}$, $T_j = +25^\circ\text{C}$, $V_{DD} = 5.0\text{V}$
			-	2.3	4.0		$I_{OUT} = 1.0\text{mA}$, $T_j = +125^\circ\text{C}$, $V_{DD} = 5.0\text{V}$
		DATA OUT	-	200	250	V	$I_{OUT} = +200\mu\text{A}$, $V_{DD} = 5.0\text{V}$
I_{SINK}	Output pull-down current	2.0	3.5	-	mA	$V_{OUT} = 5.0\text{V}$ to V_{PP} , $V_{DD} = 5.0\text{V}$	
V_{IH}	High level logic input voltage	3.5	-	5.3	V	$V_{DD} = 5.0\text{V}$	
V_{IL}	Low level logic input voltage	-0.3	-	0.8	V	---	
I_{IH}	High level logic input current	-	0.05	0.5	μA	$V_{IN} = V_{DD}$, $V_{DD} = 5.0\text{V}$	
I_{IL}	Low level logic input current	-	-0.05	-0.5	μA	$V_{IN} = 0.8\text{V}$, $V_{DD} = 5.0\text{V}$	
I_{DDQ}	Quiescent V_{DD} supply current	-	100	300	μA	All outputs high, $V_{DD} = 5.0\text{V}$	
		-	100	300		All outputs low, $V_{DD} = 5.0\text{V}$	
I_{PPQ}	Quiescent V_{PP} supply current	-	10	100	μA	All outputs high, no load	
		-	10	100		All outputs low, no load	

AC Characteristics (over recommended operating conditions, $T_A = 25^\circ\text{C}$, unless otherwise noted)

t_{PHL}	Blanking to output delay	-	2000	-	ns	$C_L = 30\text{pF}$, 50% to 50%, $V_{DD} = 5.0\text{V}$
t_{PLH}		-	1000	-		
t_f	Output fall time	-	1450	-	ns	$C_L = 30\text{pF}$, 90% to 10%, $V_{DD} = 5.0\text{V}$
t_r	Output rise time	-	650	-	ns	$C_L = 30\text{pF}$, 10% to 90%, $V_{DD} = 5.0\text{V}$
t_{SU}	Data set-up time	75	-	-	ns	See timing diagram
t_h	Data hold time	75	-	-	ns	See timing diagram
t_{pzd}	Minimum data pulse width	150	-	-	ns	See timing diagram
t_{pwclk}	Minimum clock pulse width	150	-	-	ns	See timing diagram
t_{cks}	Minimum time between clock activation and strobe	300	-	-	ns	See timing diagram
t_{pws}	Minimum strobe pulse width	100	-	-	ns	See timing diagram
t_{sto}	Typical time between strobe activation and output transition	-	500	-	ns	See timing diagram
f_{CLK}	Maximum clock frequency	-	8.0	-	MHz	$T_j = +25^\circ\text{C}$, $V_{DD} = 5.0\text{V}$
		-	5.0	-		$T_j = +125^\circ\text{C}$, $V_{DD} = 5.0\text{V}$

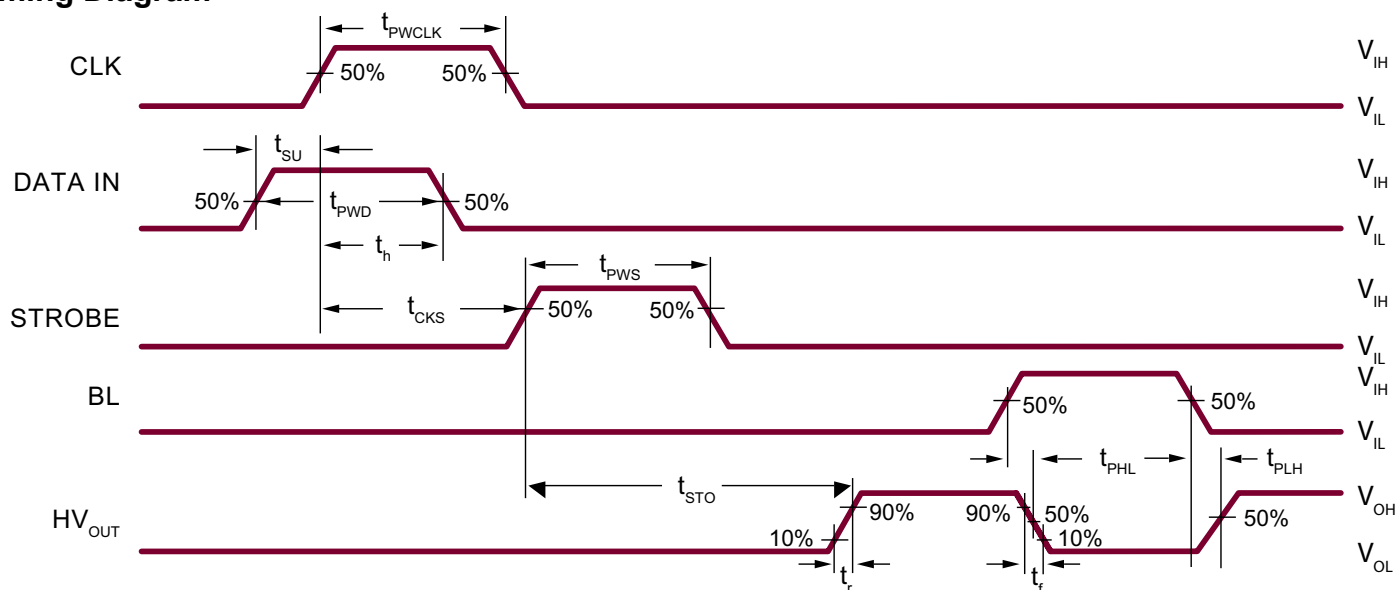
Function Table

Serial Data Input	Clock Input	Shift Register Contents					Serial Data Output	Strobe Input	Latch Content					Blanking	Output Content				
		I ₁	I ₂	I ₃ ...	I _{N-1}	I _N			I ₁	I ₂	I ₃ ...	I _{N-1}	I _N		I ₁	I ₂	I ₃ ...	I _{N-1}	I _N
H	L to H	H	R ₁	R ₂ ...	R _{N-2}	R _{N-1}	R _{N-1}	-	-	-	-	-	-	-	-	-	-	-	-
L	L to H	L	R ₁	R ₂ ...	R _{N-2}	R _{N-1}	R _{N-1}	-	-	-	-	-	-	-	-	-	-	-	-
X	H to L	R ₁	R ₂	R ₃ ...	R _{N-1}	R _N	R _N	-	-	-	-	-	-	-	-	-	-	-	-
-	-	X	X	X ...	X	X	X	L	R ₁	R ₂	R ₃ ...	R _{N-1}	R _N	-	-	-	-	-	-
-	-	P ₁	P ₂	P ₃ ...	P _{N-1}	P _N	P _N	H	P ₁	P ₂	P ₃ ...	P _{N-1}	P _N	L	P ₁	P ₂	P ₃ ...	P _{N-1}	P _N
-	-	-	-	-	-	-	-	-	X	X	X ...	X	X	H	L	L	L ...	L	L

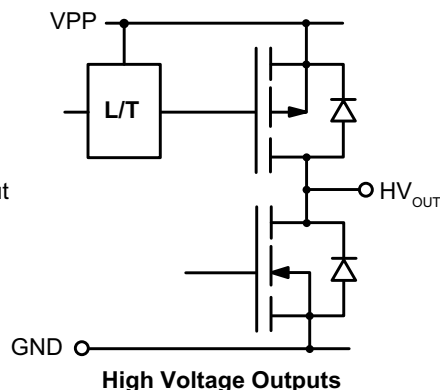
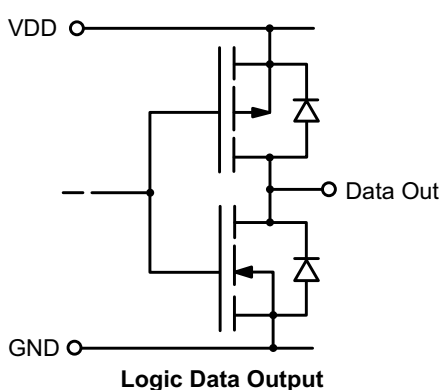
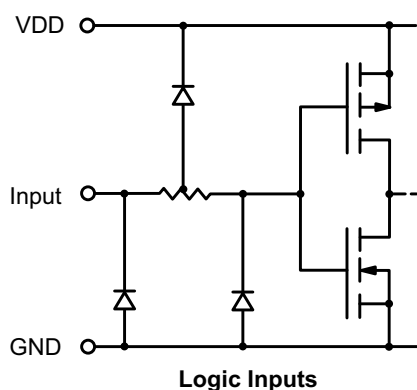
Note:

- L = Low logic level
- H = High logic level
- X = Irrelevant
- P = Present state
- R = Previous state

Timing Diagram



Input and Output Equivalent Circuits



28-Lead PDIP Pin Assignment (P)

Pin #	Function
1	VPP
2	Data Out
3	HV _{OUT} 20
4	HV _{OUT} 19
5	HV _{OUT} 18
6	HV _{OUT} 17
7	HV _{OUT} 16
8	HV _{OUT} 15
9	HV _{OUT} 14
10	HV _{OUT} 13

Pin #	Function
11	HV _{OUT} 12
12	HV _{OUT} 11
13	BLANKING
14	GND
15	CLOCK
16	STROBE
17	HV _{OUT} 10
18	HV _{OUT} 9
19	HV _{OUT} 8
20	HV _{OUT} 7

Pin #	Function
21	HV _{OUT} 6
22	HV _{OUT} 5
23	HV _{OUT} 4
24	HV _{OUT} 3
25	HV _{OUT} 2
26	HV _{OUT} 1
27	Data In
28	VDD

28-Lead PLCC Pin Assignment (PJ)

Pin #	Function
1	VPP
2	Data Out
3	HV _{OUT} 20
4	HV _{OUT} 19
5	HV _{OUT} 18
6	HV _{OUT} 17
7	HV _{OUT} 16
8	HV _{OUT} 15
9	HV _{OUT} 14
10	HV _{OUT} 13

Pin #	Function
11	HV _{OUT} 12
12	HV _{OUT} 11
13	BLANKING
14	GND
15	CLOCK
16	STROBE
17	HV _{OUT} 10
18	HV _{OUT} 9
19	HV _{OUT} 8
20	HV _{OUT} 7

Pin #	Function
21	HV _{OUT} 6
22	HV _{OUT} 5
23	HV _{OUT} 4
24	HV _{OUT} 3
25	HV _{OUT} 2
26	HV _{OUT} 1
27	Data In
28	VDD

28-Lead SOW Pin Assignment (WG)

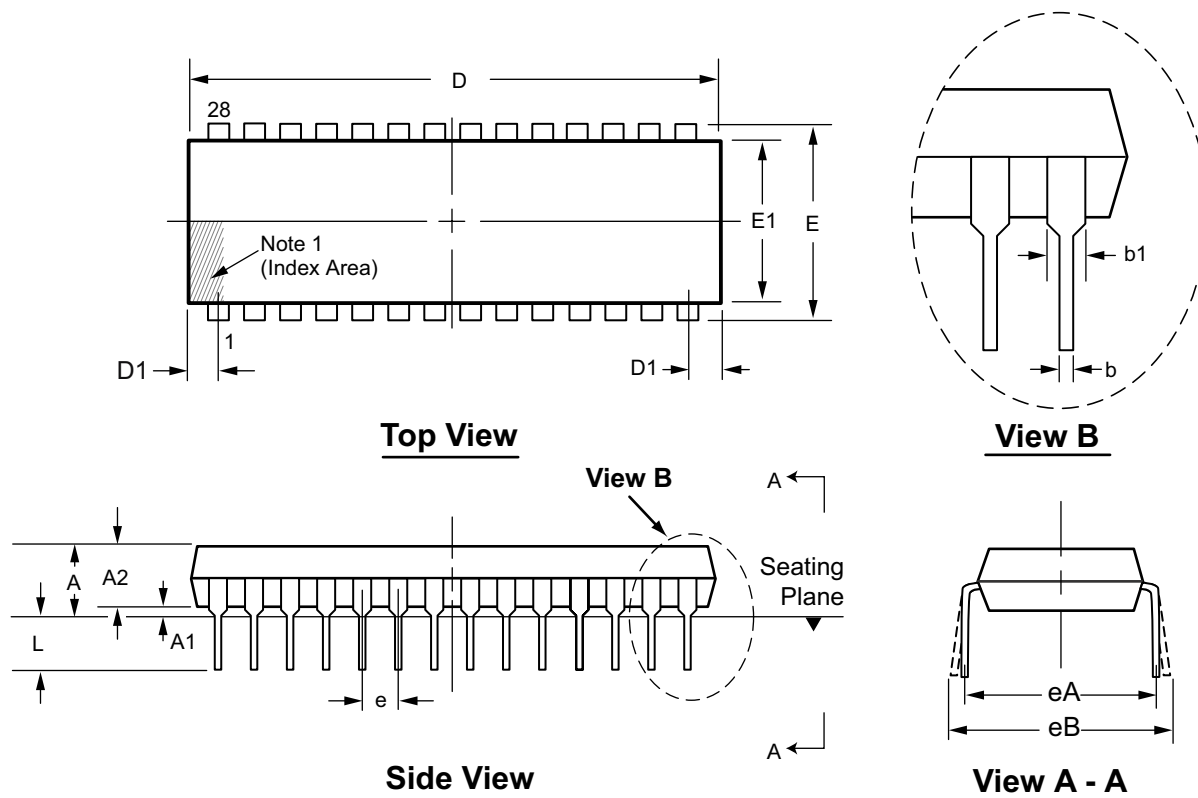
Pin #	Function
1	VPP
2	Data Out
3	HV _{OUT} 20
4	HV _{OUT} 19
5	HV _{OUT} 18
6	HV _{OUT} 17
7	HV _{OUT} 16
8	HV _{OUT} 15
9	HV _{OUT} 14
10	HV _{OUT} 13

Pin #	Function
11	HV _{OUT} 12
12	HV _{OUT} 11
13	BLANKING
14	GND
15	CLOCK
16	STROBE
17	HV _{OUT} 10
18	HV _{OUT} 9
19	HV _{OUT} 8
20	HV _{OUT} 7

Pin #	Function
21	HV _{OUT} 6
22	HV _{OUT} 5
23	HV _{OUT} 4
24	HV _{OUT} 3
25	HV _{OUT} 2
26	HV _{OUT} 1
27	Data In
28	VDD

28-Lead PDIP (.600in Row Spacing) Package Outline (P)

1.565x.580in body, .250in height (max), .100in pitch



Note:
 1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symbol	A	A1	A2	b	b1	D	D1	E	E1	e	eA	eB	L		
Dimension (inches)	MIN	.140*	.015	.125	.014	.030	1.380	.065 [†]	.590 [†]	.485	.100 BSC	.600 BSC	.600*	.115	
	NOM	-	-	-	-	-	-	-	-	-			-	-	-
	MAX	.250	.055*	.195	.023 [†]	.070	1.565	.085*	.625	.580			.700	.200	

JEDEC Registration MS-011, Variation AB, Issue B, June, 1988.

* This dimension is not specified in the JEDEC drawing.

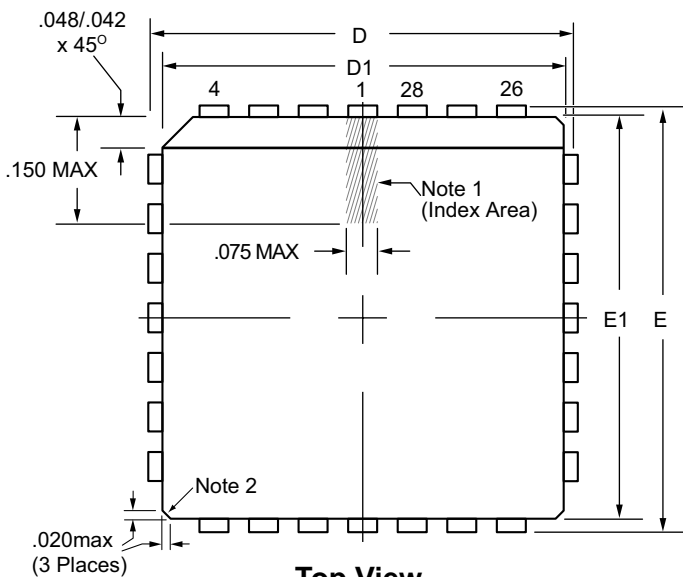
† This dimension differs from the JEDEC drawing.

Drawings not to scale.

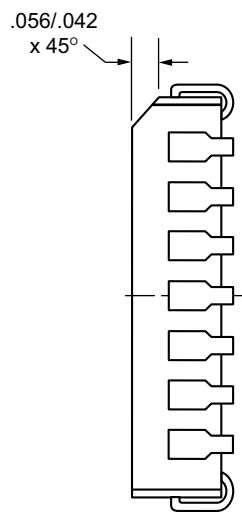
Supertex Doc. #: DSPD-28DIPP, Version B041009.

28-Lead PLCC Package Outline (PJ)

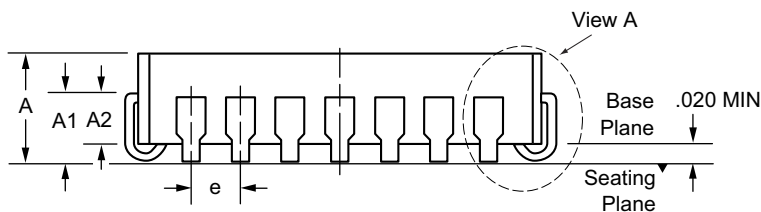
.453x.453in. body, .180in. height (max), .050in. pitch



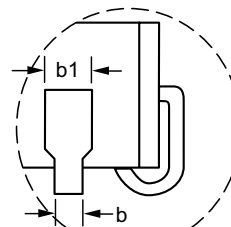
Top View



Vertical Side View



Horizontal Side View



View A

Notes:

1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.
2. Actual shape of this feature may vary.

Symbol	A	A1	A2	b	b1	D	D1	E	E1	e	
Dimension (inches)	MIN	.165	.090	.062	.013	.026	.485	.450	.485	.450	.050 BSC
	NOM	.172	.105	-	-	-	.490	.453	.490	.453	
	MAX	.180	.120	.083	.021	.032	.495	.456	.495	.456	

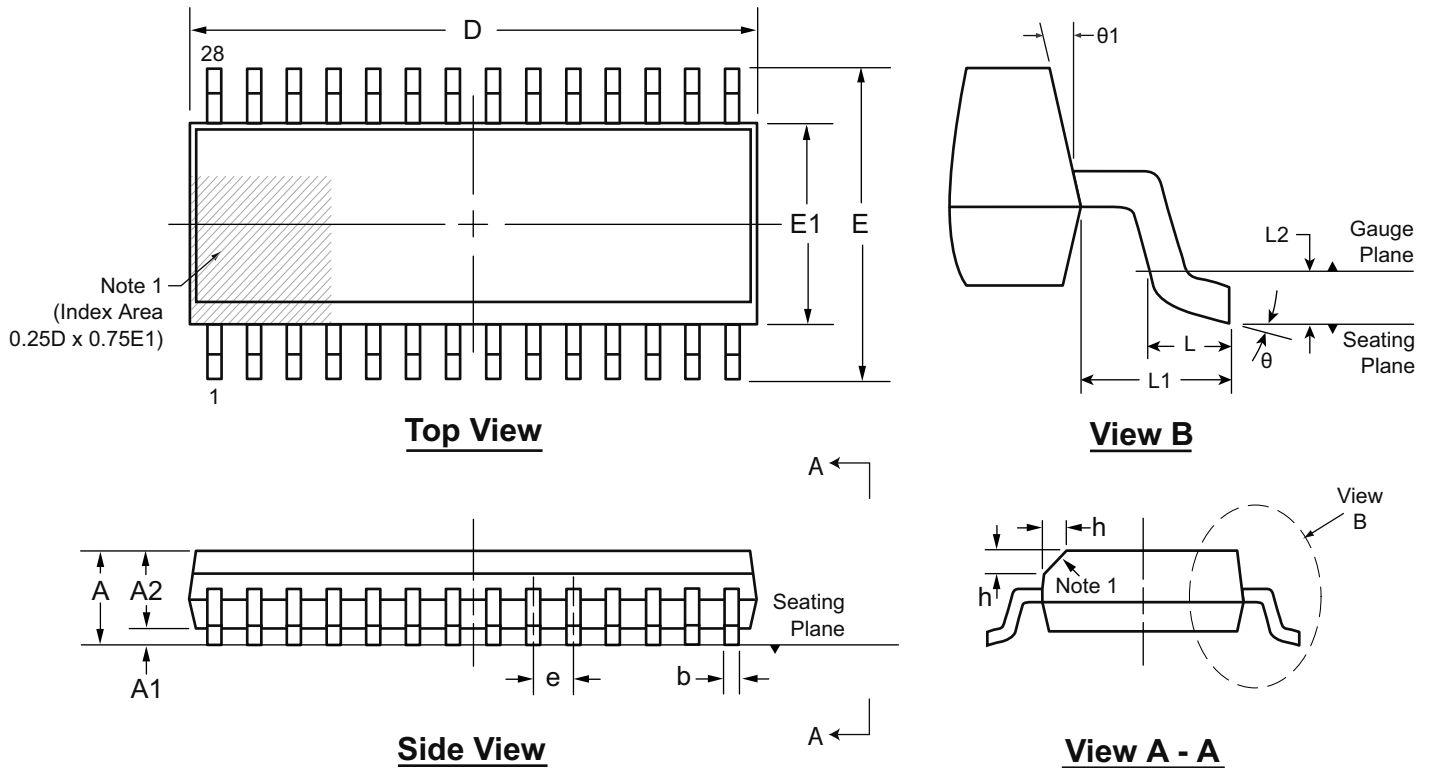
JEDEC Registration MS-018, Variation AB, Issue A, June, 1993.

Drawings not to scale.

Supertex Doc. #: DSPD-28PLCCPJ, Version A092408.

28-Lead SOW (Wide Body) Package Outline (WG)

17.90x7.50mm body, 2.65mm height (max), 1.27mm pitch



Note:
 1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symbol	A	A1	A2	b	D	E	E1	e	h	L	L1	L2	θ	θ1	
Dimension (mm)	MIN	2.15*	0.10	2.05	0.31	17.70*	9.97*	7.40*	1.27 BSC	0.25	0.40	1.40 REF	0.25	5°	
	NOM	-	-	-	-	17.90	10.30	7.50		-	-		0.25 BSC	-	-
	MAX	2.65	0.30	2.55*	0.51	18.10*	10.63*	7.60*		0.75	1.27		8°	15°	

JEDEC Registration MS-013, Variation AE, Issue E, Sep. 2005.

* This dimension is not specified in the JEDEC drawing.

Drawings are not to scale.

Supertex Doc. #: DSPD-28SOWWG, Version D041309.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <http://www.supertex.com/packaging.html>.)

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